



**Materials Declaration**

<b>Package</b>	TSOT
<b>Body Size</b>	--
<b>LeadCount</b>	5
<b>Option</b>	Pb-Free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
OCN	16	9.49 E-04	63559
SiO2	80	4.74 E-03	317793
Sb2O3	2.4	1.42 E-04	9534
Br	0.6	3.56 E-05	2383
Carbon Black	1	5.93 E-05	3972

Molding Compound		
Item	PPM	Method
Pb	<10.38	ICP AES
Cd	0.0039	ICP AES
Hg	Not Detected	ICP AES
Cr+6	Not Detected	DIN 53314

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Fe	58.4	3.80 E-03	254288
Ni	41	2.67 E-03	178524
Mn	0.4	2.60 E-05	1742
Si	0.2	1.30 E-05	871

Die Attach Paste		
Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

Internal Leadframe Plating			
	% of Plating	Weight (g)	PPM
Ag	100	1.00 E-04	6699

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	100	6.70 E-04	44882

Bond Wires			
	% of Wire	Weight (g)	PPM
Au	99.99	5.00 E-04	33484

Chip			
	% of Chip	Weight (g)	PPM
Si	100	8.00 E-04	53591

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Resin	25	1.07 E-04	7170
Ag Filler	75	3.21 E-04	21510

Package Totals	
Weight (g)	PPM
1.49 E-02	1000000

CRS-UJ-C

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

5/31/04





**Materials Declaration**

<b>Package</b>	TSOT
<b>Body Size</b>	--
<b>LeadCount</b>	5
<b>Option</b>	Sn/Pb

Molding Compound			
Item	% of Compound	Weight (g)	PPM
OCN	16	9.49 E-04	63559
SiO2	80	4.74 E-03	317793
Sb2O3	2.4	1.42 E-04	9534
Br	0.6	3.56 E-05	2383
Carbon Black	1	5.93 E-05	3972

Molding Compound		
Item	PPM	Method
Pb	<10.38	ICP AES
Cd	0.0039	ICP AES
Hg	Not Detected	ICP AES
Cr+6	Not Detected	DIN 53314

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Fe	58.4	3.80 E-03	254288
Ni	41	2.67 E-03	178524
Mn	0.4	2.60 E-05	1742
Si	0.2	1.30 E-05	871

Die Attach Paste		
Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

Internal Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Ag	100	1.00 E-04	6699

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	85	5.70 E-04	38150
Pb	15	1.01 E-04	6732

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	5.00 E-04	33484

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100	8.00 E-04	53591

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Resin	25	1.07 E-04	7170
Ag Filler	75	3.21 E-04	21510

Package Totals	
Weight (g)	PPM
1.49 E-02	1000000

CRS-UJ-A

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

5/31/04

